



MARKET FOCUS

SESSIONS

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CALL FOR SPEAKERS

In our 18th year, Market Focus stands as a highlight of the ECOC Exhibition, attracting top industry speakers from around the globe. It remains the go-to source for up-to-date industry insights, covering key technical areas and the latest in optical communications trends.

Our Market Focus sessions for 2024 are carefully selected to encompass the full technology value chain, spanning optical components to network providers in both telecommunications and data center/data communication services. With the recent rise of G-AI (Generative-Artificial Intelligence), increased investment in hyperscaler equipment build-out, and accelerated roadmaps for higher speed, lower power consumption photonics and electronics; this year's Market Focus sessions will address the current dynamics of the optical networking industry.

Our advisory committee is composed of industry experts who will review all submitted abstracts to plan another exciting Market Focus in Frankfurt in 2024.

Chaired by **Michael Lebby** from Lightwave Logic, the highly industrial and commercially experienced committee includes:

Pierpaolo Ghiggino Industry Consultant, *Wladek Forsysiak* of Aston University, *Stephan Neidlinger* from Adtran, *Daryl Inniss* from OFS, *Glenn Wellbrock* from Verizon, *Frank Chang* from Source Photonics, *Bill Ring* from Vector Photonics, and *Karen Liu* from Nubis Communications Inc.

If you are interested in speaking at the ECOC Market Focus please visit www.ecocexhibition.com/visit/market-focus/ to submit your abstract stating your company name, position, topic of interest and a 100 word summary of your presentation theme with a title based on one of the topics below, by **Tuesday 11th June 2024**.

MARKET FOCUS 2024 TOPICS

Service providers/media/social companies

1. Impact of social and media on the internet/network
2. State of the optical transport markets (metro, long haul, submarine) and OTN trends
3. Transmission roadmaps (route to 100s Tbps and associated MSAs/standards efforts)
4. Energy Efficient Ethernet and green datacenters
5. Power impact of co-packaging (CPO) vs. pluggable platforms
6. Scaling capacity and growth with DWDM super-channels
7. OTN Design & planning software
8. Embedded network monitoring, testing, and diagnostics
9. Network sustainability

Networking/systems/DC/disaggregated solutions/software

1. Fibre access (5G) and next generation 6G/7G systems
2. Operator business models (regulation, standards, installation, mgt etc.)
3. High speed PON and FTTH solutions (cables, antennas, coherent etc.)
4. Future trends for server/switch designs and architectures in the datacenter
5. Network architectures and wavelength routing and gridless architectures
6. Colourless, directionless, contentionless ROADM networks
7. Network automation and SDN standards/industry groups
8. Network disaggregation: Open terminals, Optical Line Systems, white boxes

Modules/sub-systems/connectors/line-cards

1. Advanced fiber-based connector/interfaces/panels
2. Competitive modules for WDM / high-speed PON
3. PIC based transceivers (pluggable and co-packaged/CPO)
4. Architecture trends for line cards, faceplate, rack data throughput
5. Intelligent sensors/sensing using fiber communications
6. Agile transceivers (data rate, wavelength, modulation scheme, coherent/coherent-lite, FEC, etc.)
7. Embedded optics/waveguides in pcbs and associated interposers
8. Chip-to-chip communications (fiber and/or optical wireless) Integrated (Black Box) vs. Disaggregated platforms
9. White box networking architectures/trends/technology platforms

Components/ICs/PICs/fiber

1. Classic component performance (discrete and integrated photonics), ROADMs
2. High speed, low power modulators (polymer, TFLN, plasmonic, Silicon, InP etc.)
3. Tunable and fixed wavelength devices
4. Future PIC trends, roadmaps, complexity with InP, silicon photonics, polymers
5. VCSELs: high speed, arrays, smart pixels
6. Electronics (and associated modulation techniques – PAM, QPSK, QAM etc.) for lightwave (DSPs, ASICs, computational processing)
7. Advanced packaging trends (low cost, high speed, volume driven, CoB, FC, interposers) and associated testing techniques

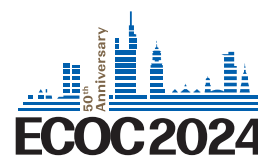
New and emerging technologies

1. 3D structured light and sensing
2. Transportation, remote, and distributed sensing
3. Optical radars or lidar
4. Bio-medical applications
5. Multicore fibre
6. Satellite and free space optics
7. Automotive (LIDAR) sensing optics, beam steering, phased array optics
8. Ultra-short (<10m) distance data communications, AOC and parallel optics
9. Projection optics (home and cinema/conference applications)
10. Novel PICs and photonic devices/materials and platforms
11. Optical switching materials/components
12. New technologies
13. Liquid or Immersion cooling
14. New 1.6T & 3.2T optics

2 roundtables/panels*

1. Chaired by Jose Pozo, Optica
2. Chaired by Frank Chang, Source Photonics

*panel speakers will be invited by the Market Focus committee



THE ECOC EXHIBITION
23-25 September 2024, Messe Frankfurt, Germany
www.ecocexhibition.com